

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

1. (Original) A cleaner that is an aqueous solution containing phosphoric acid, hydrofluoric acid, and ammonia and/or amine and having a pH ranging from 2 to 12, wherein said aqueous solution contains:

0.5 to 25 mass% of phosphoric acid,

0.1 to 10 mass% of ammonia and/or amine, and

5×10^{-3} to 5.0 mass% of hydrofluoric acid.

2. (Currently amended) The cleaner according to claim [[2]]1, wherein the pH is regulated by phosphoric acid.

3. (Original) The cleaner according to claim 1 or 2, which further includes a surface active agent and/or a chelate agent.

4. (Currently amended) The ~~cleaner~~ cleaner according to claim 1, which further includes hydrogen peroxide.

5. (Previously presented) The cleaner according to claim 1, which is used for cleaning off particles and/or metal impurities out of the surface of a semiconductor device substrate.

6. (Currently amended) The ~~cleaner~~ cleaner according to claim 2, which further includes hydrogen peroxide.

7. (Currently amended) The ~~cleaner~~ cleaner according to claim 3, which further includes hydrogen peroxide.

8. (Previously presented) The cleaner according to claim 2, which is used for cleaning off particles and/or metal impurities out of the surface of a semiconductor device substrate.

9. (Previously presented) The cleaner according to claim 3, which is used for cleaning off particles and/or metal impurities out of the surface of a semiconductor device substrate.

10. (Previously presented) The cleaner according to claim 4, which is used for cleaning off particles and/or metal impurities out of the surface of a semiconductor device substrate.